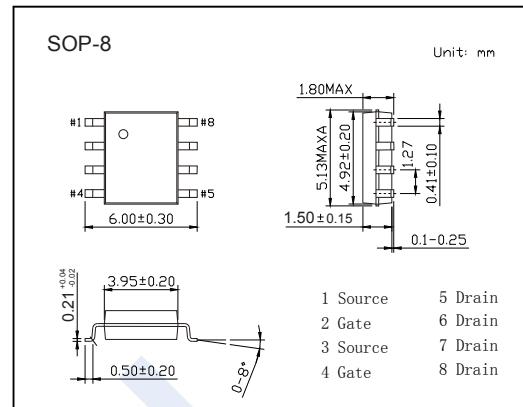
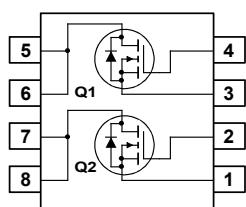


## Dual N-Channel MOSFET

### SI9926DY-HF (KI9926DY-HF)

#### ■ Features

- $V_{DS}(V) = 20V$
- $I_D = 6.5 A$  ( $V_{GS} = 4.5V$ )
- $R_{DS(ON)} < 30m\Omega$  ( $V_{GS} = 4.5V$ )
- $R_{DS(ON)} < 43m\Omega$  ( $V_{GS} = 2.5V$ )
- Low gate charge
- Pb-Free Package May be Available. The G-Suffix Denotes a Pb-Free Lead Finish



#### ■ Absolute Maximum Ratings $T_a = 25^\circ C$

Parameter	Symbol	Rating	Unit
Drain-Source Voltage	$V_{DS}$	20	V
Gate-Source Voltage	$V_{GS}$	$\pm 10$	
Continuous Drain Current (Note.1)	$I_D$	6.5	A
Pulsed Drain Current	$I_{DM}$	20	
Power Dissipation for Dual Operation (Note.1)	$P_D$	2	W
Power Dissipation for Single Operation (Note.2)		1.6	
(Note.3)		1	
Thermal Resistance.Junction- to-Ambient (Note.1)	$R_{thJA}$	78	
Thermal Resistance.Junction- to-Case	$R_{thJC}$	40	$^\circ C/W$
Junction Temperature	$T_J$	150	
Storage Temperature Range	$T_{stg}$	-55 to 150	$^\circ C$

Note.1:  $78^\circ/W$  when mounted on a  $0.5in^2$  pad of 2 oz copper

Note.2:  $125^\circ/W$  when mounted on a  $0.02 in^2$  pad of 2 oz copper

Note.3:  $135^\circ/W$  when mounted on a minimum pad.

## Dual N-Channel MOSFET

### SI9926DY-HF (KI9926DY-HF)

■ Electrical Characteristics  $T_a = 25^\circ C$

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Drain-Source Breakdown Voltage	$V_{DSS}$	$I_D=250 \mu A, V_{GS}=0V$	20			V
Zero Gate Voltage Drain Current	$I_{DS(on)}$	$V_{DS}=16V, V_{GS}=0V$			1	$\mu A$
Gate-Body Leakage Current	$I_{GSS}$	$V_{DS}=0V, V_{GS}=\pm 10V$			$\pm 100$	nA
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_D=250 \mu A$ (Note.1)	0.5		1.5	V
Static Drain-Source On-Resistance (Note.1)	$R_{DS(on)}$	$V_{GS}=4.5V, I_D=6.5A$			30	$m\Omega$
		$V_{GS}=4.5V, I_D=6.5A, T_J=125^\circ C$			50	
		$V_{GS}=2.5V, I_D=5.4A$			43	
On State Drain Current	$I_{D(on)}$	$V_{GS}=4.5V, V_{DS}=5V$ (Note.1)	15			A
Forward Transconductance	$g_{FS}$	$V_{DS}=5V, I_D=3A$ (Note.1)		11		S
Input Capacitance	$C_{iss}$	$V_{GS}=0V, V_{DS}=10V, f=1MHz$		700		$pF$
Output Capacitance	$C_{oss}$			175		
Reverse Transfer Capacitance	$C_{rss}$			85		
Total Gate Charge	$Q_g$	$V_{GS}=4.5V, V_{DS}=10V, I_D=3A$ (Note.1)		7	10	$nC$
Gate Source Charge	$Q_{gs}$			1.2		
Gate Drain Charge	$Q_{gd}$			1.9		
Turn-On Delay Time	$t_{d(on)}$	$V_{GS}=4.5V, V_{DS}=100V, I_D=1A, R_G=6 \Omega$ (Note.1)		8	16	$ns$
Turn-On Rise Time	$t_r$			10	18	
Turn-Off Delay Time	$t_{d(off)}$			18	29	
Turn-Off Fall Time	$t_f$			5	10	
Maximum Body-Diode Continuous Current	$I_S$				1.3	A
Diode Forward Voltage	$V_{SD}$	$I_S=1.3A, V_{GS}=0V$ (Note.1)			1.2	V

Note.1: Pulse Test: Pulse Width < 300us, Duty Cycle < 2.0%

■ Marking

Marking	9926 KA**** F
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## Dual N-Channel MOSFET

### SI9926DY-HF (KI9926DY-HF)

■ Typical Characteristics

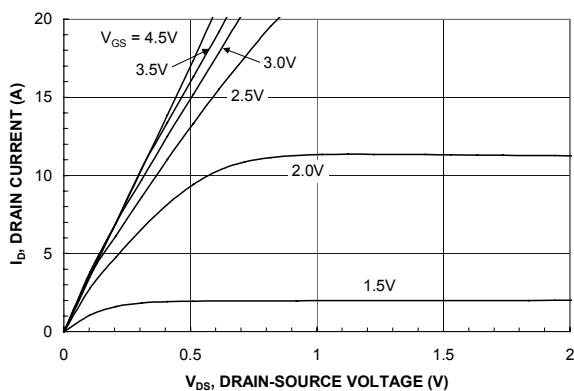


Figure 1. On-Region Characteristics.

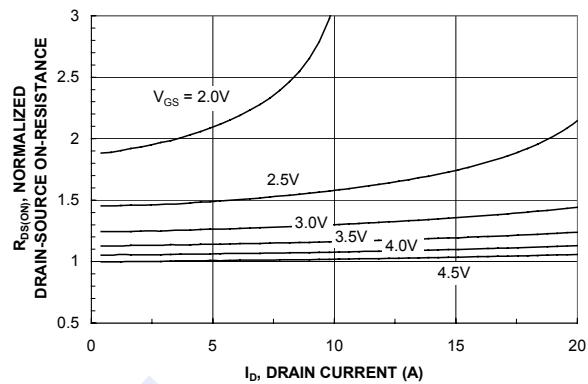


Figure 2. On-Resistance Variation with Drain Current and Gate Voltage.

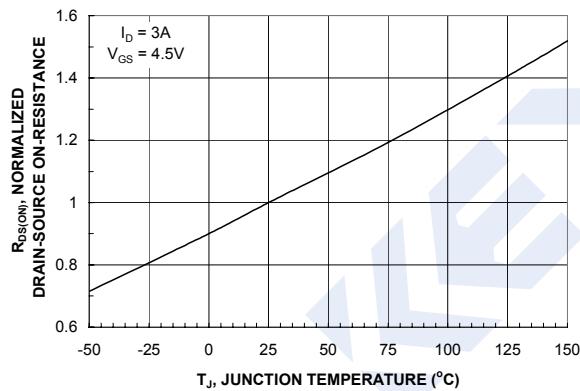


Figure 3. On-Resistance Variation with Temperature.

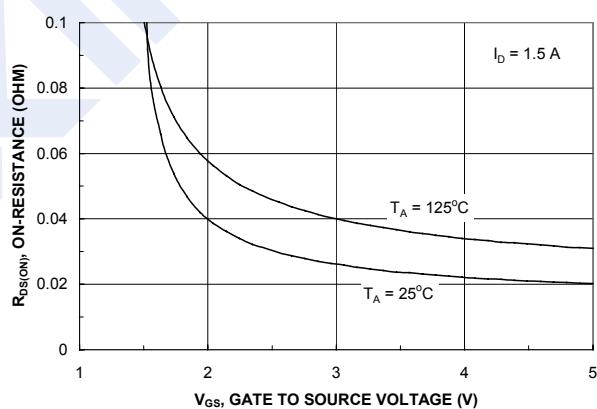


Figure 4. On-Resistance Variation with Gate-to-Source Voltage.

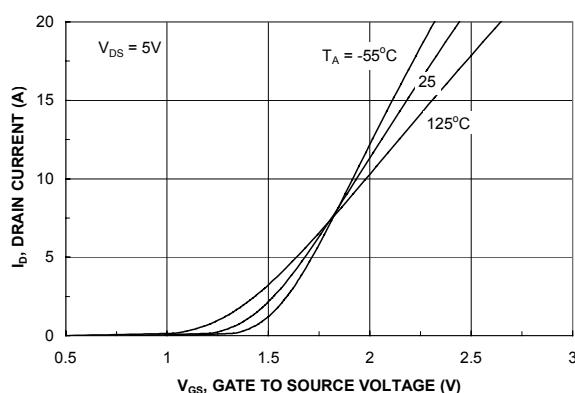


Figure 5. Transfer Characteristics.

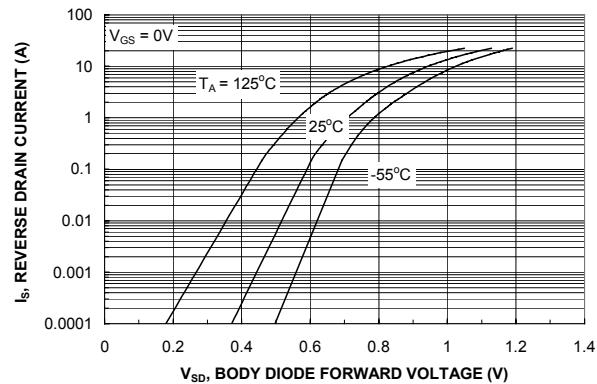
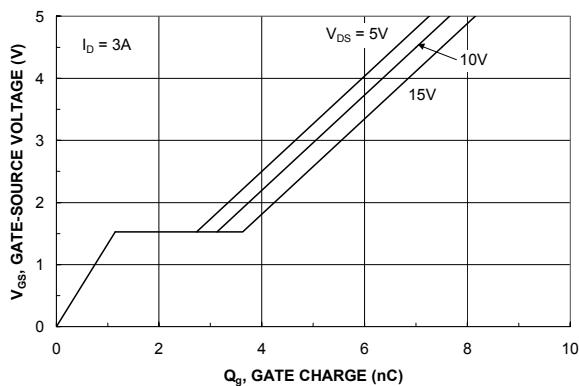


Figure 6. Body Diode Forward Voltage Variation with Source Current and Temperature.

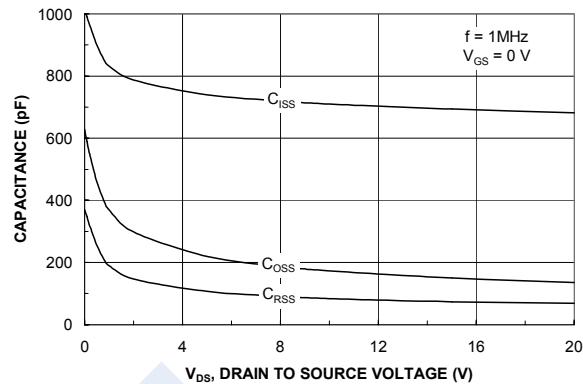
## Dual N-Channel MOSFET

### SI9926DY-HF (KI9926DY-HF)

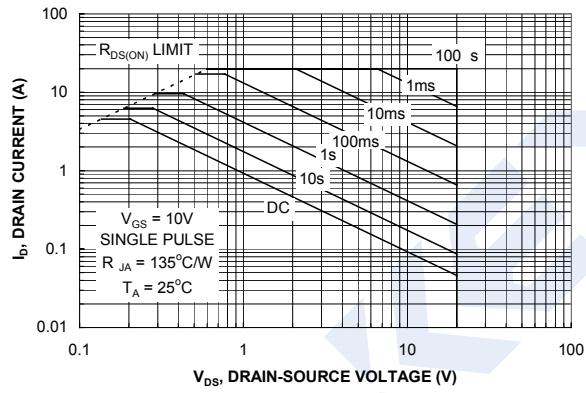
■ Typical Characteristics



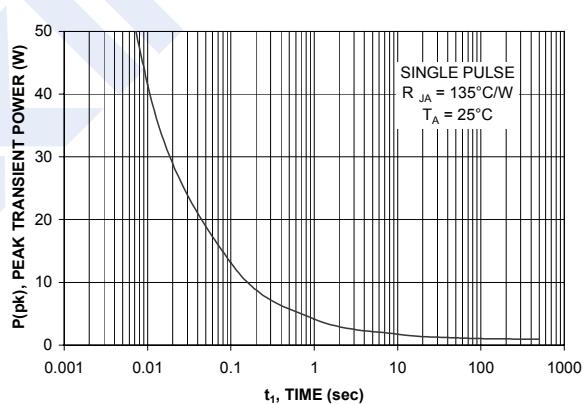
**Figure 7. Gate Charge Characteristics.**



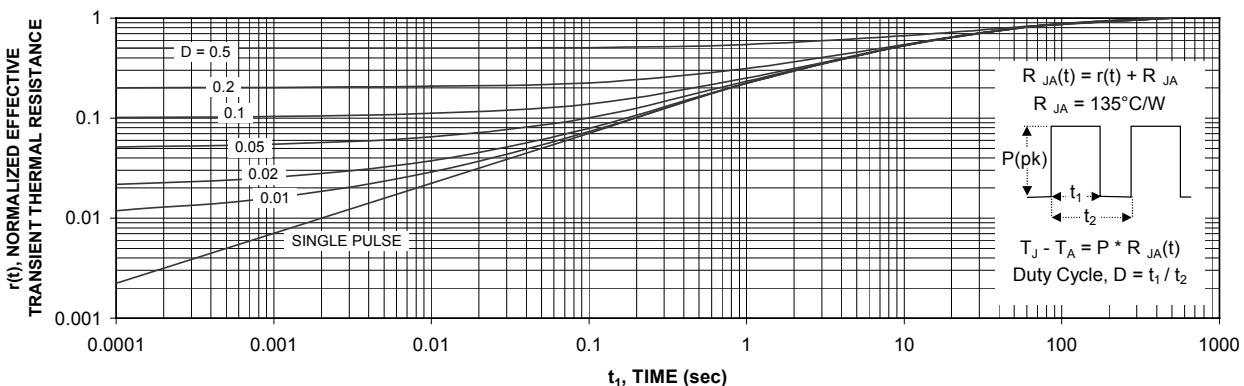
**Figure 8. Capacitance Characteristics.**



**Figure 9. Maximum Safe Operating Area.**



**Figure 10. Single Pulse Maximum Power Dissipation.**



**Figure 11. Transient Thermal Response Curve.**

Thermal characterization performed using the conditions described in Note 1c.  
Transient thermal response will change depending on the circuit board design.